

| L Number | Hits   | Search Text  | DB  | Time stamp       |
|----------|--------|--|---|------------------|
| 1        | 1490   | ((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out)))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:03 |
| 2        | 128    | ((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out))) with pad   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:49 |
| 3        | 73     | ((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out))) with pad) and array  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:49 |
| 4        | 67     | ((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out))) with pad) and array) and (semiconductor chip die)                              | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:59 |
| 5        | 479    | leadless near1 package   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:56 |
| 6        | 193    | (leadless near1 package) and (pad land) and array  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:57 |
| 7        | 192    | ((leadless near1 package) and (pad land) and array) not (((substrate ((circuit wiring) near board)) with (trace pattern) with (layout (laid adj out))) with pad) and array)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:57 |
| 8        | 138    | ((leadless near1 package) and (pad land) and array) and (bump ball)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:58 |
| 9        | 130    | ((leadless near1 package) and (pad land) and array) and (bump ball)) and (pattern trace wiring wire)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:59 |
| 10       | 115    | ((leadless near1 package) and (pad land) and array) and (bump ball)) and (pattern trace wiring)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:58 |
| 11       | 127    | ((leadless near1 package) and (pad land) and array) and (bump ball)) and (pattern trace wiring wire)) and (semiconductor chip die)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 07:59 |
| 12       | 336004 | (substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:04 |
| 13       | 46520  | (bond bonding conductive) adj (land pad)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:28 |
| 14       | 8635   | ((bond bonding conductive) adj (land pad)) with (shape shaped configuration structure)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:28 |
| 15       | 3085   | ((substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)) and ((bond bonding conductive) adj (land pad)) with (shape shaped configuration structure))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:07 |
| 16       | 3579   | ((bond bonding conductive) adj (land pad)) near3 (shape shaped configuration structure)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:07 |
| 17       | 1307   | ((substrate carrier ((circuit wiring) near board)) with (trace pattern wiring)) and ((bond bonding conductive) adj (land pad)) near3 (shape shaped configuration structure)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:08 |

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|----|------|--|---|------------------|
| 18 | 1669 | ((bond bonding conductive) adj (land pad))<br>near3 (shape shaped configuration)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:08 |
| 19 | 689  | ((substrate carrier ((circuit wiring) near<br>board)) with (trace pattern wiring)) and<br>(((bond bonding conductive) adj (land<br>pad)) near3 (shape shaped configuration))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:08 |
| 22 | 181  | (((substrate carrier ((circuit wiring)<br>near board)) with (trace pattern wiring))<br>and ((bond bonding conductive) adj (land<br>pad)) near3 (shape shaped configuration)))<br>and (grid near array)) not (((substrate<br>((circuit wiring) near board)) with (trace<br>pattern) with (layout (laid adj out)))<br>with pad) and array) not (((leadless<br>near1 package) and (pad land) and array)<br>and (bump ball)) and (pattern trace wiring<br>wire)) and (semiconductor chip die)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:10 |
| 21 | 189  | (((substrate carrier ((circuit wiring)<br>near board)) with (trace pattern wiring))<br>and ((bond bonding conductive) adj (land<br>pad)) near3 (shape shaped configuration)))<br>and (grid near array)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:10 |
| 23 | 13   | ("5477082"   "5491303"   "5517041"  <br>"5535101"   "5585675"   "5640048"  <br>"5666024"   "5764485"   "5875102"  <br>"6107109"   "6310398"   "6380060"  <br>"6403460"   "2002/0149102").PN.   | USPAT                                       | 2004/03/11 08:13 |
| 24 | 13   | ("5477082"   "5491303"   "5517041"  <br>"5535101"   "5585675"   "5640048"  <br>"5666024"   "5764485"   "5875102"  <br>"6107109"   "6310398"   "6380060"  <br>"6403460"   "2002/0149102").PN.   | USPAT                                       | 2004/03/11 08:15 |
| 20 | 20   | ((bond bonding conductive) adj (land<br>pad)) near3 (shape shaped configuration))<br>with stress   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:25 |
| 25 | 1279 | (bond bonding conductive) adj land   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:28 |
| 26 | 115  | ((bond bonding conductive) adj land) with<br>(shape shaped configuration)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:30 |
| 27 | 67   | ((substrate carrier ((circuit wiring) near<br>board)) with (trace pattern wiring)) and<br>(((bond bonding conductive) adj land) with<br>(shape shaped configuration))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:30 |
| 28 | 25   | (((substrate carrier ((circuit wiring)<br>near board)) with (trace pattern wiring))<br>and ((bond bonding conductive) adj land)<br>with (shape shaped configuration))) and<br>stress   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT | 2004/03/11 08:30 |
| 29 | 9    | ("3871015"   "4801998"   "5186383"  <br>"5269453"   "5326794"   "5346118"  <br>"5381307"   "5400950"   "5576362").PN.  | USPAT                                       | 2004/03/11 08:32 |
| 30 | 8    | 6091155.URPN.  | USPAT                                       | 2004/03/11 08:37 |